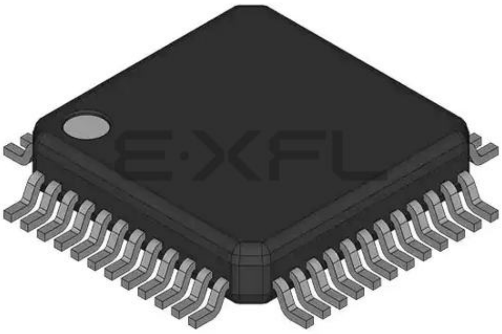


Details	
Product Status	Obsolete
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	CANbus, I²C, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	39
Program Memory Size	60KB (60K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	3K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc9s08dv60amlf

[1] ACMP2O is not available.

1.2 MCU Block Diagram

Figure 1-1 is the MC9S08DV60 Series system-level block diagram.

2.2.1 Power

V_{DD} and V_{SS} are the primary power supply pins for the MCU. This voltage source supplies power to all I/O buffer circuitry and to an internal voltage regulator. The internal voltage regulator provides regulated lower-voltage source to the CPU and other internal circuitry of the MCU.

Typically, application systems have two separate capacitors across the power pins. In this case, there should be a bulk electrolytic capacitor, such as a 10-µF tantalum capacitor, to provide bulk charge storage for the overall system and a 0.1-µF ceramic bypass capacitor located as near to the MCU power pins as practical to suppress high-frequency noise. The MC9S08DV60 Series has two V_{DD} pins except on the 32-pin package. Each pin must have a bypass capacitor for best noise suppression.

V_{DDA} and V_{SSA} are the analog power supply pins for the MCU. This voltage source supplies power to the ADC module. A 0.1-µF ceramic bypass capacitor should be located as near to the MCU power pins as practical to suppress high-frequency noise.

2.2.2 Oscillator

Immediately after reset, the MCU uses an internally generated clock provided by the multi-purpose clock generator (MCG) module. For more information on the MCG, see Chapter 8, “Multi-Purpose Clock Generator (S08MCGV1).”

The oscillator (XOSC) in this MCU is a Pierce oscillator that can accommodate a crystal or ceramic resonator. Rather than a crystal or ceramic resonator, an external oscillator can be connected to the EXTAL input pin.

Refer to Figure 2-4 for the following discussion. R_S (when used) and R_F should be low-inductance resistors such as carbon composition resistors. Wire-wound resistors and some metal film resistors have too much inductance. C1 and C2 normally should be high-quality ceramic capacitors that are specifically designed for high-frequency applications.

R_F is used to provide a bias path to keep the EXTAL input in its linear range during crystal startup; its value is not generally critical. Typical systems use 1 MΩ to 10 MΩ. Higher values are sensitive to humidity, and lower values reduce gain and (in extreme cases) could prevent startup.

C1 and C2 are typically in the 5-pF to 25-pF range and are chosen to match the requirements of a specific crystal or resonator. Be sure to take into account printed circuit board (PCB) capacitance and MCU pin capacitance when selecting C1 and C2. The crystal manufacturer typically specifies a load capacitance which is the series combination of C1 and C2 (which are usually the same size). As a first-order approximation, use 10 pF as an estimate of combined pin and PCB capacitance for each oscillator pin (EXTAL and XTAL).

2.2.3 $\overline{\text{RESET}}$

$\overline{\text{RESET}}$ is a dedicated pin with a pull-up device built in. It has input hysteresis, a high current output driver, and no output slew rate control. Internal power-on reset and low-voltage reset circuitry typically make external reset circuitry unnecessary. This pin is normally connected to the standard 6-pin background debug connector so a development system can directly reset the MCU system. If desired, a manual external reset can be added by supplying a simple switch to ground (pull reset pin low to force a reset).

4.5.4 Burst Program Execution

The burst program command is used to program sequential bytes of data in less time than would be required using the standard program command. This is possible because the high voltage to the Flash array does not need to be disabled between program operations. Ordinarily, when a program or erase command is issued, an internal charge pump associated with the Flash memory must be enabled to supply high voltage to the array. Upon completion of the command, the charge pump is turned off. When a burst program command is issued, the charge pump is enabled and remains enabled after completion of the burst program operation if these two conditions are met:

- The next burst program command sequence has begun before the FCCF bit is set.
- The next sequential address selects a byte on the same burst block as the current byte being programmed. A burst block in this Flash memory consists of 32 bytes. A new burst block begins at each 32-byte address boundary.

The first byte of a series of sequential bytes being programmed in burst mode will take the same amount of time to program as a byte programmed in standard mode. Subsequent bytes will program in the burst program time provided that the conditions above are met. If the next sequential address is the beginning of a new row, the program time for that byte will be the standard time instead of the burst time. This is because the high voltage to the array must be disabled and then enabled again. If a new burst command has not been queued before the current command completes, then the charge pump will be disabled and high voltage removed from the array.

A flowchart to execute the burst program operation is shown in Figure 4-3.

4.5.10 Flash Registers and Control Bits

The Flash module has seven 8-bit registers in the high-page register space and three locations in the nonvolatile register space in Flash memory. Two of those locations are copied into two corresponding high-page control registers at reset. There is also an 8-byte comparison key in Flash memory. Refer to Table 4-3 and Table 4-5 for the absolute address assignments for all Flash registers. This section refers to registers and control bits only by their names. A Freescale Semiconductor-provided equate or header file normally is used to translate these names into the appropriate absolute addresses.

4.5.10.1 Flash Clock Divider Register (FCDIV)

Bit 7 of this register is a read-only flag. Bits 6:0 may be read at any time but can be written only one time. Before any erase or programming operations are possible, write to this register to set the frequency of the clock for the nonvolatile memory system within acceptable limits.

	7	6	5	4	3	2	1	0
R	DIVLD	PRDIV8	DIV					
W	▨							
Reset	0	0	0	0	0	0	0	0

▨ = Unimplemented or Reserved

Figure 4-5. Flash Clock Divider Register (FCDIV)

Table 4-7. FCDIV Register Field Descriptions

Field	Description
7 DIVLD	**Divisor Loaded Status Flag** — When set, this read-only status flag indicates that the FCDIV register has been written since reset. Reset clears this bit and the first write to this register causes this bit to become set regardless of the data written. 0 FCDIV has not been written since reset; erase and program operations disabled for Flash. 1 FCDIV has been written since reset; erase and program operations enabled for Flash.
6 PRDIV8	**Prescale (Divide) Flash Clock by 8** (This bit is write once.) 0 Clock input to the Flash clock divider is the bus rate clock. 1 Clock input to the Flash clock divider is the bus rate clock divided by 8.
5:0 DIV	**Divisor for Flash Clock Divider** — These bits are write once. The Flash clock divider divides the bus rate clock (or the bus rate clock divided by 8 if PRDIV8 = 1) by the value in the 6-bit DIV field plus one. The resulting frequency of the internal Flash clock must fall within the range of 200 kHz to 150 kHz for proper Flash operations. Program/Erase timing pulses are one cycle of this internal Flash clock which corresponds to a range of 5 μs to 6.7 μs. The automated programming logic uses an integer number of these pulses to complete an erase or program operation. See Equation 4-1 and Equation 4-2.

$$\text{if PRDIV8} = 0 \text{ — } f_{FCLK} = f_{Bus} \div (DIV + 1) \qquad \textit{Eqn. 4-1}$$

$$\text{if PRDIV8} = 1 \text{ — } f_{FCLK} = f_{Bus} \div (8 \times (DIV + 1)) \qquad \textit{Eqn. 4-2}$$

Table 4-8 shows the appropriate values for PRDIV8 and DIV for selected bus frequencies.

6.5.2.3 Port B Pull Enable Register (PTBPE)

	7	6	5	4	3	2	1	0
R W	PTBPE7	PTBPE6	PTBPE5	PTBPE4	PTBPE3	PTBPE2	PTBPE1	PTBPE0
Reset:	0	0	0	0	0	0	0	0

Figure 6-13. Internal Pull Enable for Port B Register (PTBPE)

Table 6-11. PTBPE Register Field Descriptions

Field	Description
7:0 PTBPE[7:0]	**Internal Pull Enable for Port B Bits** — Each of these control bits determines if the internal pull-up or pull-down device is enabled for the associated PTB pin. For port B pins that are configured as outputs, these bits have no effect and the internal pull devices are disabled. 0 Internal pull-up/pull-down device disabled for port B bit n. 1 Internal pull-up/pull-down device enabled for port B bit n.

NOTE

Pull-down devices only apply when using pin interrupt functions, when corresponding edge select and pin select functions are configured.

6.5.2.4 Port B Slew Rate Enable Register (PTBSE)

	7	6	5	4	3	2	1	0
R W	PTBSE7	PTBSE6	PTBSE5	PTBSE4	PTBSE3	PTBSE2	PTBSE1	PTBSE0
Reset:	0	0	0	0	0	0	0	0

Figure 6-14. Slew Rate Enable for Port B Register (PTBSE)

Table 6-12. PTBSE Register Field Descriptions

Field	Description
7:0 PTBSE[7:0]	**Output Slew Rate Enable for Port B Bits** — Each of these control bits determines if the output slew rate control is enabled for the associated PTB pin. For port B pins that are configured as inputs, these bits have no effect. 0 Output slew rate control disabled for port B bit n. 1 Output slew rate control enabled for port B bit n.

Note: Slew rate reset default values may differ between engineering samples and final production parts. Always initialize slew rate control to the desired value to ensure correct operation.

7.2.3 Stack Pointer (SP)

This 16-bit address pointer register points at the next available location on the automatic last-in-first-out (LIFO) stack. The stack may be located anywhere in the 64-Kbyte address space that has RAM and can be any size up to the amount of available RAM. The stack is used to automatically save the return address for subroutine calls, the return address and CPU registers during interrupts, and for local variables. The AIS (add immediate to stack pointer) instruction adds an 8-bit signed immediate value to SP. This is most often used to allocate or deallocate space for local variables on the stack.

SP is forced to 0x00FF at reset for compatibility with the earlier M68HC05 Family. HCS08 programs normally change the value in SP to the address of the last location (highest address) in on-chip RAM during reset initialization to free up direct page RAM (from the end of the on-chip registers to 0x00FF).

The RSP (reset stack pointer) instruction was included for compatibility with the M68HC05 Family and is seldom used in new HCS08 programs because it only affects the low-order half of the stack pointer.

7.2.4 Program Counter (PC)

The program counter is a 16-bit register that contains the address of the next instruction or operand to be fetched.

During normal program execution, the program counter automatically increments to the next sequential memory location every time an instruction or operand is fetched. Jump, branch, interrupt, and return operations load the program counter with an address other than that of the next sequential location. This is called a change-of-flow.

During reset, the program counter is loaded with the reset vector that is located at 0xFFFE and 0xFFFF. The vector stored there is the address of the first instruction that will be executed after exiting the reset state.

7.2.5 Condition Code Register (CCR)

The 8-bit condition code register contains the interrupt mask (I) and five flags that indicate the results of the instruction just executed. Bits 6 and 5 are set permanently to 1. The following paragraphs describe the functions of the condition code bits in general terms. For a more detailed explanation of how each instruction sets the CCR bits, refer to the *HCS08 Family Reference Manual, volume 1,* Freescale Semiconductor document order number HCS08RMv1.

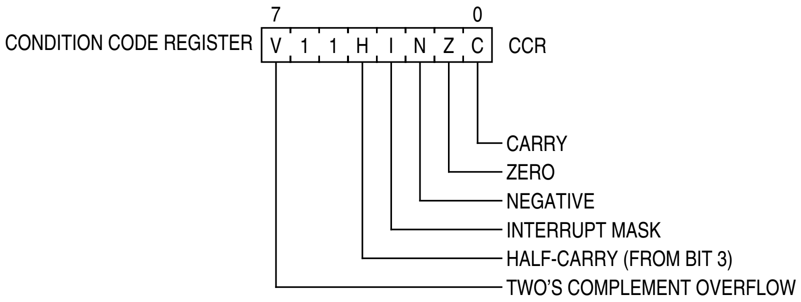


Figure 7-2. Condition Code Register

Table 7-1. CCR Register Field Descriptions

Field	Description
7 V	**Two's Complement Overflow Flag** — The CPU sets the overflow flag when a two's complement overflow occurs. The signed branch instructions BGT, BGE, BLE, and BLT use the overflow flag. 0 No overflow 1 Overflow
4 H	**Half-Carry Flag** — The CPU sets the half-carry flag when a carry occurs between accumulator bits 3 and 4 during an add-without-carry (ADD) or add-with-carry (ADC) operation. The half-carry flag is required for binary-coded decimal (BCD) arithmetic operations. The DAA instruction uses the states of the H and C condition code bits to automatically add a correction value to the result from a previous ADD or ADC on BCD operands to correct the result to a valid BCD value. 0 No carry between bits 3 and 4 1 Carry between bits 3 and 4
3 I	**Interrupt Mask Bit** — When the interrupt mask is set, all maskable CPU interrupts are disabled. CPU interrupts are enabled when the interrupt mask is cleared. When a CPU interrupt occurs, the interrupt mask is set automatically after the CPU registers are saved on the stack, but before the first instruction of the interrupt service routine is executed. Interrupts are not recognized at the instruction boundary after any instruction that clears I (CLI or TAP). This ensures that the next instruction after a CLI or TAP will always be executed without the possibility of an intervening interrupt, provided I was set. 0 Interrupts enabled 1 Interrupts disabled
2 N	**Negative Flag** — The CPU sets the negative flag when an arithmetic operation, logic operation, or data manipulation produces a negative result, setting bit 7 of the result. Simply loading or storing an 8-bit or 16-bit value causes N to be set if the most significant bit of the loaded or stored value was 1. 0 Non-negative result 1 Negative result
1 Z	**Zero Flag** — The CPU sets the zero flag when an arithmetic operation, logic operation, or data manipulation produces a result of 0x00 or 0x0000. Simply loading or storing an 8-bit or 16-bit value causes Z to be set if the loaded or stored value was all 0s. 0 Non-zero result 1 Zero result
0 C	**Carry/Borrow Flag** — The CPU sets the carry/borrow flag when an addition operation produces a carry out of bit 7 of the accumulator or when a subtraction operation requires a borrow. Some instructions — such as bit test and branch, shift, and rotate — also clear or set the carry/borrow flag. 0 No carry out of bit 7 1 Carry out of bit 7

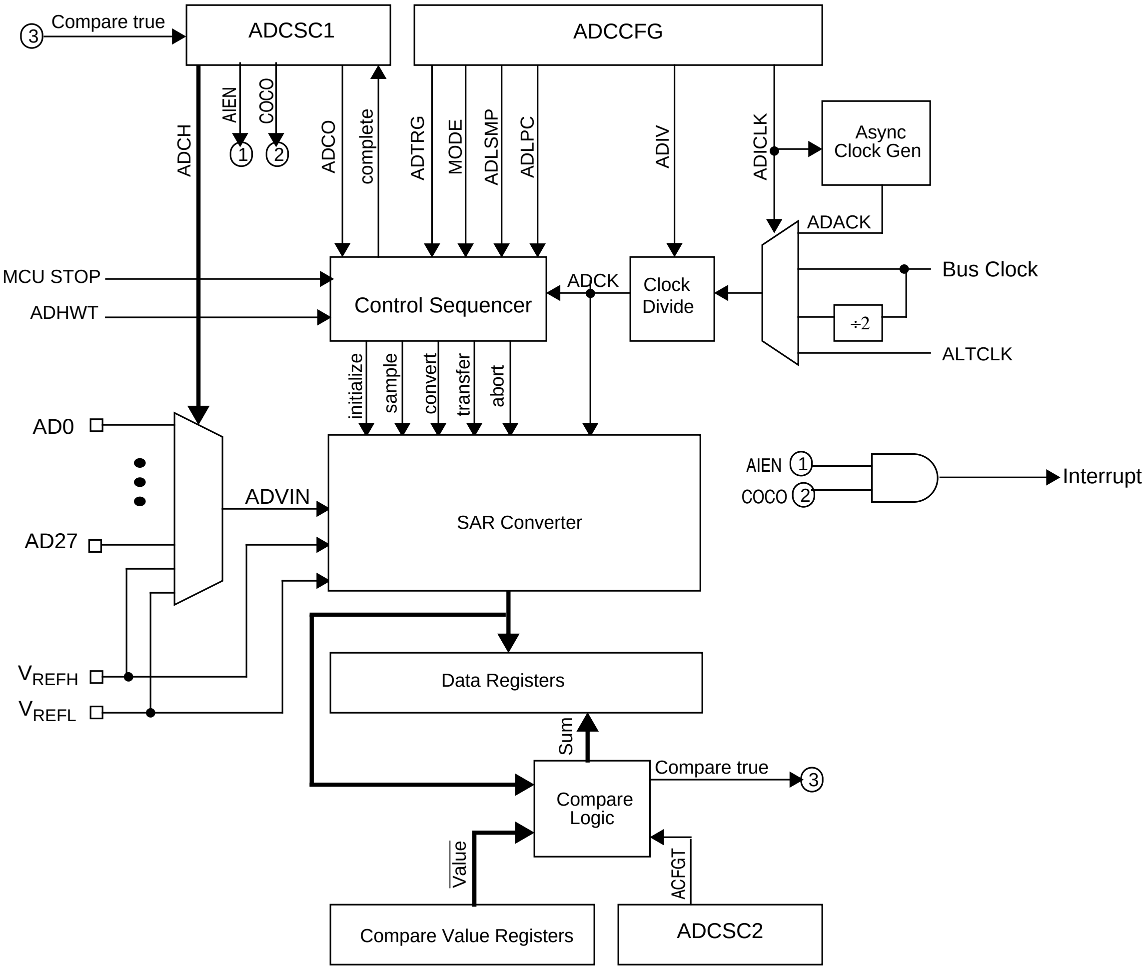


Figure 10-2. ADC Block Diagram

10.2 External Signal Description

The ADC module supports up to 28 separate analog inputs. It also requires four supply/reference/ground connections.

Table 10-2. Signal Properties

Name	Function
AD27–AD0	Analog Channel inputs
V_{REFH}	High reference voltage
V_{REFL}	Low reference voltage
V_{DDAD}	Analog power supply
V_{SSAD}	Analog ground

When a conversion is aborted, the contents of the data registers, ADCRH and ADCRL, are not altered. However, they continue to be the values transferred after the completion of the last successful conversion. If the conversion was aborted by a reset, ADCRH and ADCRL return to their reset states.

10.4.4.4 Power Control

The ADC module remains in its idle state until a conversion is initiated. If ADACK is selected as the conversion clock source, the ADACK clock generator is also enabled.

Power consumption when active can be reduced by setting ADLPC. This results in a lower maximum value for f_{ADCK} (see the electrical specifications).

10.4.4.5 Sample Time and Total Conversion Time

The total conversion time depends on the sample time (as determined by ADLSMP), the MCU bus frequency, the conversion mode (8-bit, 10-bit or 12-bit), and the frequency of the conversion clock (f_{ADCK}). After the module becomes active, sampling of the input begins. ADLSMP selects between short (3.5 ADCK cycles) and long (23.5 ADCK cycles) sample times.When sampling is complete, the converter is isolated from the input channel and a successive approximation algorithm is performed to determine the digital value of the analog signal. The result of the conversion is transferred to ADCRH and ADCRL upon completion of the conversion algorithm.

If the bus frequency is less than the f_{ADCK} frequency, precise sample time for continuous conversions cannot be guaranteed when short sample is enabled (ADLSMP=0). If the bus frequency is less than 1/11th of the f_{ADCK} frequency, precise sample time for continuous conversions cannot be guaranteed when long sample is enabled (ADLSMP=1).

The maximum total conversion time for different conditions is summarized in Table 10-13.

Table 10-13. Total Conversion Time vs. Control Conditions

Conversion Type	ADICLK	ADLSMP	Max Total Conversion Time
Single or first continuous 8-bit	0x, 10	0	20 ADCK cycles + 5 bus clock cycles
Single or first continuous 10-bit or 12-bit	0x, 10	0	23 ADCK cycles + 5 bus clock cycles
Single or first continuous 8-bit	0x, 10	1	40 ADCK cycles + 5 bus clock cycles
Single or first continuous 10-bit or 12-bit	0x, 10	1	43 ADCK cycles + 5 bus clock cycles
Single or first continuous 8-bit	11	0	5 μs + 20 ADCK + 5 bus clock cycles
Single or first continuous 10-bit or 12-bit	11	0	5 μs + 23 ADCK + 5 bus clock cycles
Single or first continuous 8-bit	11	1	5 μs + 40 ADCK + 5 bus clock cycles
Single or first continuous 10-bit or 12-bit	11	1	5 μs + 43 ADCK + 5 bus clock cycles
Subsequent continuous 8-bit; $f_{BUS} \geq f_{ADCK}$	xx	0	17 ADCK cycles
Subsequent continuous 10-bit or 12-bit; $f_{BUS} \geq f_{ADCK}$	xx	0	20 ADCK cycles
Subsequent continuous 8-bit; $f_{BUS} \geq f_{ADCK}/11$	xx	1	37 ADCK cycles

NOTE

The CANRFLG register is held in the reset state[1] when the initialization mode is active (INITRQ = 1 and INITAK = 1). This register is writable again as soon as the initialization mode is exited (INITRQ = 0 and INITAK = 0).

Read: Anytime

Write: Anytime when out of initialization mode, except RSTAT[1:0] and TSTAT[1:0] flags which are read-only; write of 1 clears flag; write of 0 is ignored.

Table 12-9. CANRFLG Register Field Descriptions

Field	Description
7 WUPIF	**Wake-Up Interrupt Flag** — If the MSCAN detects CAN bus activity while in sleep mode (see Section 12.5.5.4, “MSCAN Sleep Mode,”) and WUPE = 1 in CANTCTL0 (see Section 12.3.1, “MSCAN Control Register 0 (CANCTL0)”), the module will set WUPIF. If not masked, a wake-up interrupt is pending while this flag is set. 0 No wake-up activity observed while in sleep mode 1 MSCAN detected activity on the CAN bus and requested wake-up
6 CSCIF	**CAN Status Change Interrupt Flag** — This flag is set when the MSCAN changes its current CAN bus status due to the actual value of the transmit error counter (TEC) and the receive error counter (REC). An additional 4-bit (RSTAT[1:0], TSTAT[1:0]) status register, which is split into separate sections for TEC/REC, informs the system on the actual CAN bus status (see Section 12.3.5, “MSCAN Receiver Interrupt Enable Register (CANRIER)”). If not masked, an error interrupt is pending while this flag is set. CSCIF provides a blocking interrupt. That guarantees that the receiver/transmitter status bits (RSTAT/TSTAT) are only updated when no CAN status change interrupt is pending. If the TECs/RECs change their current value after the CSCIF is asserted, which would cause an additional state change in the RSTAT/TSTAT bits, these bits keep their status until the current CSCIF interrupt is cleared again. 0 No change in CAN bus status occurred since last interrupt 1 MSCAN changed current CAN bus status
5:4 RSTAT[1:0]	**Receiver Status Bits** — The values of the error counters control the actual CAN bus status of the MSCAN. As soon as the status change interrupt flag (CSCIF) is set, these bits indicate the appropriate receiver related CAN bus status of the MSCAN. The coding for the bits RSTAT1, RSTAT0 is: 00 RxOK: 0 ≤ receive error counter ≤ 96 01 RxWRN: 96 < receive error counter ≤ 127 10 RxERR: 127 < receive error counter 11 Bus-off[1]: transmit error counter > 255
3:2 TSTAT[1:0]	**Transmitter Status Bits** — The values of the error counters control the actual CAN bus status of the MSCAN. As soon as the status change interrupt flag (CSCIF) is set, these bits indicate the appropriate transmitter related CAN bus status of the MSCAN. The coding for the bits TSTAT1, TSTAT0 is: 00 TxOK: 0 ≤ transmit error counter ≤ 96 01 TxWRN: 96 < transmit error counter ≤ 127 10 TxERR: 127 < transmit error counter ≤ 255 11 Bus-Off: transmit error counter > 255

---

[1] The RSTAT[1:0], TSTAT[1:0] bits are not affected by initialization mode.

12.3.14 MSCAN Transmit Error Counter (CANTXERR)

This register reflects the status of the MSCAN transmit error counter.

	7	6	5	4	3	2	1	0
R	TXERR7	TXERR6	TXERR5	TXERR4	TXERR3	TXERR2	TXERR1	TXERR0
W	▨	▨	▨	▨	▨	▨	▨	▨
Reset:	0	0	0	0	0	0	0	0

▨ = Unimplemented

Figure 12-18. MSCAN Transmit Error Counter (CANTXERR)

Read: Only when in sleep mode (SLPRQ = 1 and SLPAK = 1) or initialization mode (INITRQ = 1 and INITAK = 1)

Write: Unimplemented

NOTE

> Reading this register when in any other mode other than sleep or initialization mode, may return an incorrect value. For MCUs with dual CPUs, this may result in a CPU fault condition.
>
> Writing to this register when in special modes can alter the MSCAN functionality.

12.3.15 MSCAN Identifier Acceptance Registers (CANIDAR0-7)

On reception, each message is written into the background receive buffer. The CPU is only signalled to read the message if it passes the criteria in the identifier acceptance and identifier mask registers (accepted); otherwise, the message is overwritten by the next message (dropped).

The acceptance registers of the MSCAN are applied on the IDR0–IDR3 registers (see Section 12.4.1, "Identifier Registers (IDR0–IDR3)") of incoming messages in a bit by bit manner (see Section 12.5.3, "Identifier Acceptance Filter").

For extended identifiers, all four acceptance and mask registers are applied. For standard identifiers, only the first two (CANIDAR0/1, CANIDMR0/1) are applied.

	7	6	5	4	3	2	1	0
R W	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
Reset	0	0	0	0	0	0	0	0

Figure 12-19. MSCAN Identifier Acceptance Registers (First Bank) — CANIDAR0–CANIDAR3

Read: Anytime

Write: Anytime in initialization mode (INITRQ = 1 and INITAK = 1)

The MSCAN then schedules the message for transmission and signals the successful transmission of the buffer by setting the associated TXE flag. A transmit interrupt (see Section 12.5.7.2, "Transmit Interrupt") is generated[1] when TXEx is set and can be used to drive the application software to re-load the buffer.

If more than one buffer is scheduled for transmission when the CAN bus becomes available for arbitration, the MSCAN uses the local priority setting of the three buffers to determine the prioritization. For this purpose, every transmit buffer has an 8-bit local priority field (PRIO). The application software programs this field when the message is set up. The local priority reflects the priority of this particular message relative to the set of messages being transmitted from this node. The lowest binary value of the PRIO field is defined to be the highest priority. The internal scheduling process takes place whenever the MSCAN arbitrates for the CAN bus. This is also the case after the occurrence of a transmission error.

When a high priority message is scheduled by the application software, it may become necessary to abort a lower priority message in one of the three transmit buffers. Because messages that are already in transmission cannot be aborted, the user must request the abort by setting the corresponding abort request bit (ABTRQ) (see Section 12.3.8, "MSCAN Transmitter Message Abort Request Register (CANTARQ)".) The MSCAN then grants the request, if possible, by:

1. Setting the corresponding abort acknowledge flag (ABTAK) in the CANTAAK register.
2. Setting the associated TXE flag to release the buffer.
3. Generating a transmit interrupt. The transmit interrupt handler software can determine from the setting of the ABTAK flag whether the message was aborted (ABTAK = 1) or sent (ABTAK = 0).

12.5.2.3 Receive Structures

The received messages are stored in a five stage input FIFO. The five message buffers are alternately mapped into a single memory area (see Figure 12-38). The background receive buffer (RxBG) is exclusively associated with the MSCAN, but the foreground receive buffer (RxFG) is addressable by the CPU (see Figure 12-38). This scheme simplifies the handler software because only one address area is applicable for the receive process.

All receive buffers have a size of 15 bytes to store the CAN control bits, the identifier (standard or extended), the data contents, and a time stamp, if enabled (see Section 12.4, "Programmer's Model of Message Storage").

The receiver full flag (RXF) (see Section 12.3.4.1, "MSCAN Receiver Flag Register (CANRFLG)") signals the status of the foreground receive buffer. When the buffer contains a correctly received message with a matching identifier, this flag is set.

On reception, each message is checked to see whether it passes the filter (see Section 12.5.3, "Identifier Acceptance Filter") and simultaneously is written into the active RxBG. After successful reception of a valid message, the MSCAN shifts the content of RxBG into the receiver FIFO[2], sets the RXF flag, and generates a receive interrupt (see Section 12.5.7.3, "Receive Interrupt") to the CPU[3]. The user's receive handler must read the received message from the RxFG and then reset the RXF flag to acknowledge the interrupt and to release the foreground buffer. A new message, which can follow immediately after the IFS

---

[1] The transmit interrupt occurs only if not masked. A polling scheme can be applied on TXEx also.

[2] Only if the RXF flag is not set.

[3] The receive interrupt occurs only if not masked. A polling scheme can be applied on RXF also.

Table 14-7. SCIxS2 Field Descriptions (continued)

Field	Description
1 LBKDE	**LIN Break Detection Enable**— LBKDE is used to select a longer break character detection length. While LBKDE is set, framing error (FE) and receive data register full (RDRF) flags are prevented from setting. 0 Break character is detected at length of 10 bit times (11 if M = 1). 1 Break character is detected at length of 11 bit times (12 if M = 1).
0 RAF	**Receiver Active Flag** — RAF is set when the SCI receiver detects the beginning of a valid start bit, and RAF is cleared automatically when the receiver detects an idle line. This status flag can be used to check whether an SCI character is being received before instructing the MCU to go to stop mode. 0 SCI receiver idle waiting for a start bit. 1 SCI receiver active (RxD input not idle).

[1] Setting RXINV inverts the RxD input for all cases: data bits, start and stop bits, break, and idle.

When using an internal oscillator in a LIN system, it is necessary to raise the break detection threshold by one bit time. Under the worst case timing conditions allowed in LIN, it is possible that a 0x00 data character can appear to be 10.26 bit times long at a slave which is running 14% faster than the master. This would trigger normal break detection circuitry which is designed to detect a 10 bit break symbol. When the LBKDE bit is set, framing errors are inhibited and the break detection threshold changes from 10 bits to 11 bits, preventing false detection of a 0x00 data character as a LIN break symbol.

14.2.6 SCI Control Register 3 (SCIxC3)

	7	6	5	4	3	2	1	0
R	R8	T8	TXDIR	TXINV	ORIE	NEIE	FEIE	PEIE
W	▨							
Reset	0	0	0	0	0	0	0	0

▨ = Unimplemented or Reserved

Figure 14-10. SCI Control Register 3 (SCIxC3)

Table 14-8. SCIxC3 Field Descriptions

Field	Description
7 R8	**Ninth Data Bit for Receiver** — When the SCI is configured for 9-bit data (M = 1), R8 can be thought of as a ninth receive data bit to the left of the MSB of the buffered data in the SCIxD register. When reading 9-bit data, read R8 before reading SCIxD because reading SCIxD completes automatic flag clearing sequences which could allow R8 and SCIxD to be overwritten with new data.
6 T8	**Ninth Data Bit for Transmitter** — When the SCI is configured for 9-bit data (M = 1), T8 may be thought of as a ninth transmit data bit to the left of the MSB of the data in the SCIxD register. When writing 9-bit data, the entire 9-bit value is transferred to the SCI shift register after SCIxD is written so T8 should be written (if it needs to change from its previous value) before SCIxD is written. If T8 does not need to change in the new value (such as when it is used to generate mark or space parity), it need not be written each time SCIxD is written.
5 TXDIR	**TxD Pin Direction in Single-Wire Mode** — When the SCI is configured for single-wire half-duplex operation (LOOPS = RSRC = 1), this bit determines the direction of data at the TxD pin. 0 TxD pin is an input in single-wire mode. 1 TxD pin is an output in single-wire mode.

- Edge-aligned PWM mode

  The value of a 16-bit modulo register plus 1 sets the period of the PWM output signal. The channel value register sets the duty cycle of the PWM output signal. The user may also choose the polarity of the PWM output signal. Interrupts are available at the end of the period and at the duty-cycle transition point. This type of PWM signal is called edge-aligned because the leading edges of all PWM signals are aligned with the beginning of the period, which is the same for all channels within a TPM.
- Center-aligned PWM mode

  Twice the value of a 16-bit modulo register sets the period of the PWM output, and the channel-value register sets the half-duty-cycle duration. The timer counter counts up until it reaches the modulo value and then counts down until it reaches zero. As the count matches the channel value register while counting down, the PWM output becomes active. When the count matches the channel value register while counting up, the PWM output becomes inactive. This type of PWM signal is called center-aligned because the centers of the active duty cycle periods for all channels are aligned with a count value of zero. This type of PWM is required for types of motors used in small appliances.

This is a high-level description only. Detailed descriptions of operating modes are in later sections.

16.1.3 Block Diagram

The TPM uses one input/output (I/O) pin per channel, TPMxCHn (timer channel n) where n is the channel number (1-8). The TPM shares its I/O pins with general purpose I/O port pins (refer to I/O pin descriptions in full-chip specification for the specific chip implementation).

Figure 16-2 shows the TPM structure. The central component of the TPM is the 16-bit counter that can operate as a free-running counter or a modulo up/down counter. The TPM counter (when operating in normal up-counting mode) provides the timing reference for the input capture, output compare, and edge-aligned PWM functions. The timer counter modulo registers, TPMxMODH:TPMxMODL, control the modulo value of the counter (the values 0x0000 or 0xFFFF effectively make the counter free running). Software can read the counter value at any time without affecting the counting sequence. Any write to either half of the TPMxCNT counter resets the counter, regardless of the data value written.

16.2.1.1 EXTCLK — External Clock Source

Control bits in the timer status and control register allow the user to select nothing (timer disable), the bus-rate clock (the normal default source), a crystal-related clock, or an external clock as the clock which drives the TPM prescaler and subsequently the 16-bit TPM counter. The external clock source is synchronized in the TPM. The bus clock clocks the synchronizer; the frequency of the external source must be no more than one-fourth the frequency of the bus-rate clock, to meet Nyquist criteria and allowing for jitter.

The external clock signal shares the same pin as a channel I/O pin, so the channel pin will not be usable for channel I/O function when selected as the external clock source. It is the user's responsibility to avoid such settings. If this pin is used as an external clock source (CLKSB:CLKSA = 1:1), the channel can still be used in output compare mode as a software timer (ELSnB:ELSnA = 0:0).

16.2.1.2 TPMxCHn — TPM Channel n I/O Pin(s)

Each TPM channel is associated with an I/O pin on the MCU. The function of this pin depends on the channel configuration. The TPM pins share with general purpose I/O pins, where each pin has a port data register bit, and a data direction control bit, and the port has optional passive pullups which may be enabled whenever a port pin is acting as an input.

The TPM channel does not control the I/O pin when (ELSnB:ELSnA = 0:0) or when (CLKSB:CLKSA = 0:0) so it normally reverts to general purpose I/O control. When CPWMS = 1 (and ELSnB:ELSnA not = 0:0), all channels within the TPM are configured for center-aligned PWM and the TPMxCHn pins are all controlled by the TPM system. When CPWMS=0, the MSnB:MSnA control bits determine whether the channel is configured for input capture, output compare, or edge-aligned PWM.

When a channel is configured for input capture (CPWMS=0, MSnB:MSnA = 0:0 and ELSnB:ELSnA not = 0:0), the TPMxCHn pin is forced to act as an edge-sensitive input to the TPM. ELSnB:ELSnA control bits determine what polarity edge or edges will trigger input-capture events. A synchronizer based on the bus clock is used to synchronize input edges to the bus clock. This implies the minimum pulse width—that can be reliably detected—on an input capture pin is four bus clock periods (with ideal clock pulses as near as two bus clocks can be detected). TPM uses this pin as an input capture input to override the port data and data direction controls for the same pin.

When a channel is configured for output compare (CPWMS=0, MSnB:MSnA = 0:1 and ELSnB:ELSnA not = 0:0), the associated data direction control is overridden, the TPMxCHn pin is considered an output controlled by the TPM, and the ELSnB:ELSnA control bits determine how the pin is controlled. The remaining three combinations of ELSnB:ELSnA determine whether the TPMxCHn pin is toggled, cleared, or set each time the 16-bit channel value register matches the timer counter.

When the output compare toggle mode is initially selected, the previous value on the pin is driven out until the next output compare event—then the pin is toggled.

17.1.2 Features

Features of the BDC module include:

- Single pin for mode selection and background communications
- BDC registers are not located in the memory map
- SYNC command to determine target communications rate
- Non-intrusive commands for memory access
- Active background mode commands for CPU register access
- GO and TRACE1 commands
- BACKGROUND command can wake CPU from stop or wait modes
- One hardware address breakpoint built into BDC
- Oscillator runs in stop mode, if BDC enabled
- COP watchdog disabled while in active background mode

Features of the ICE system include:

- Two trigger comparators: Two address + read/write (R/W) or one full address + data + R/W
- Flexible 8-word by 16-bit FIFO (first-in, first-out) buffer for capture information:
  - Change-of-flow addresses or
  - Event-only data
- Two types of breakpoints:
  - Tag breakpoints for instruction opcodes
  - Force breakpoints for any address access
- Nine trigger modes:
  - Basic: A-only, A OR B
  - Sequence: A then B
  - Full: A AND B data, A AND NOT B data
  - Event (store data): Event-only B, A then event-only B
  - Range: Inside range (A ≤ address ≤ B), outside range (address < A or address > B)

17.2 Background Debug Controller (BDC)

All MCUs in the HCS08 Family contain a single-wire background debug interface that supports in-circuit programming of on-chip nonvolatile memory and sophisticated non-intrusive debug capabilities. Unlike debug interfaces on earlier 8-bit MCUs, this system does not interfere with normal application resources. It does not use any user memory or locations in the memory map and does not share any on-chip peripherals.

BDC commands are divided into two groups:

- Active background mode commands require that the target MCU is in active background mode (the user program is not running). Active background mode commands allow the CPU registers to be read or written, and allow the user to trace one user instruction at a time, or GO to the user program from active background mode.

Table A-3. Thermal Characteristics

Num	C	Rating	Symbol	Value	Unit	Temp. Code
1	D	Operating temperature range (packaged)	T_A	–40 to 125 –40 to 105 –40 to 85	°C	M V C
2	T	Maximum Junction Temperature[1]	T_J	135	°C	—
3	D	Thermal resistance[2]				
		Single-layer board				
		64-pin LQFP	θ_{JA}	69	°C/W	
		48-pin LQFP	θ_{JA}	75	°C/W	
		32-pin LQFP	θ_{JA}	80	°C/W	
		Four-Layer board				
		64-pin LQFP	θ_{JA}	51	°C/W	
		48-pin LQFP	θ_{JA}	51	°C/W	
		32-pin LQFP	θ_{JA}	52	°C/W	

[1] Junction temperature is a function of die size, on-chip power dissipation, package thermal resistance, mounting site (board) temperature, ambient temperature, air flow, power dissipation of other components on the board, and board thermal resistance.

[2] Junction to Ambient Natural Convection

The average chip-junction temperature (T_J) in °C can be obtained from:

$$T_J = T_A + (P_D \times \theta_{JA}) \qquad \textit{Eqn. A-1}$$

where:

T_A = Ambient temperature, °C

θ_{JA} = Package thermal resistance, junction-to-ambient, °C/W

$P_D = P_{int} + P_{I/O}$

$P_{int} = I_{DD} \times V_{DD}$, Watts — chip internal power

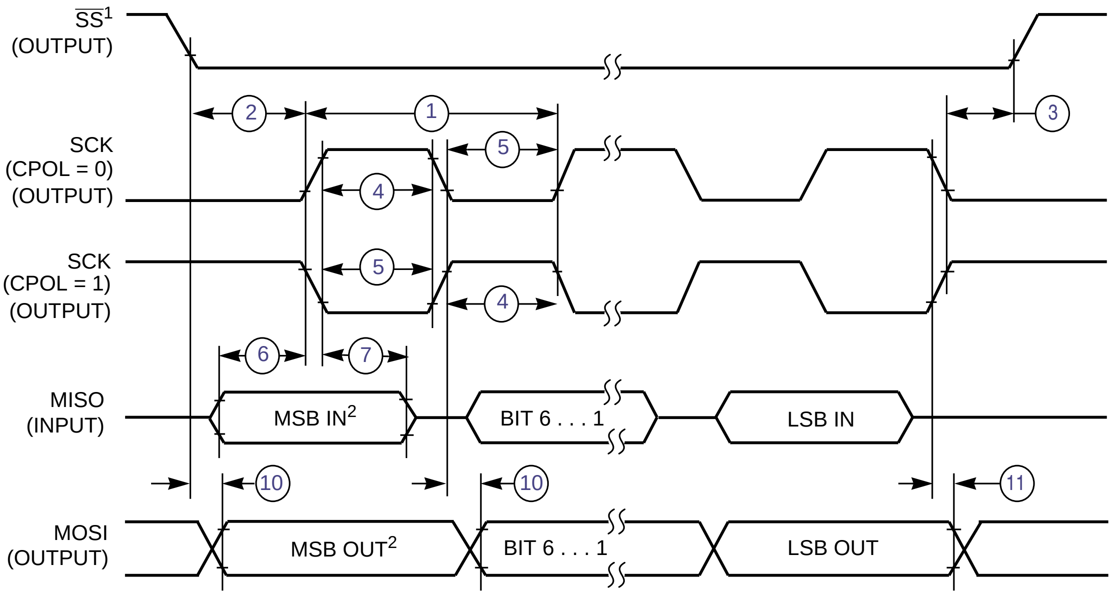
$P_{I/O}$ = Power dissipation on input and output pins — user determined

For most applications, $P_{I/O} << P_{int}$ and can be neglected. An approximate relationship between P_D and T_J (if $P_{I/O}$ is neglected) is:

$$P_D = K \div (T_J + 273°C) \qquad \textit{Eqn. A-2}$$

Solving equations 1 and 2 for K gives:

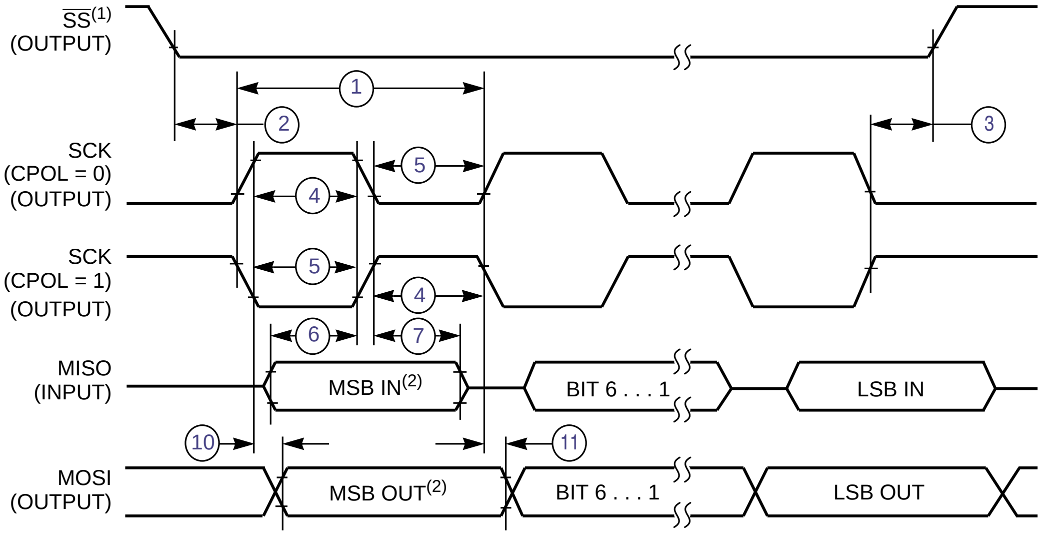
$$K = P_D \times (T_A + 273°C) + \theta_{JA} \times (P_D)^2 \qquad \textit{Eqn. A-3}$$



NOTES:

1. $\overline{SS}$ output mode (MODFEN = 1, SSOE = 1).
2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure A-7. SPI Master Timing (CPHA = 0)



NOTES:

1. $\overline{SS}$ output mode (MODFEN = 1, SSOE = 1).
2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure A-8. SPI Master Timing (CPHA = 1)

Appendix B
Timer Pulse-Width Modulator (TPMV2)

NOTE

> This chapter refers to S08TPM version 2, which applies to the 3M05C and older mask sets of this device.)M74K and newer mask set devices use S08TPM version 3. If your device uses mask 0M74K or newer, please refer to Chapter 16, "Timer Pulse-Width Modulator (S08TPMV3) for information pertaining to that module.

The TPM uses one input/output (I/O) pin per channel, TPMxCHn where x is the TPM number (for example, 1 or 2) and n is the channel number (for example, 0–4). The TPM shares its I/O pins with general-purpose I/O port pins (refer to the Pins and Connections chapter for more information).

B.0.1 Features

The TPM has the following features:

- Each TPM may be configured for buffered, center-aligned pulse-width modulation (CPWM) on all channels
- Clock sources independently selectable per TPM (multiple TPMs device)
- Selectable clock sources (device dependent): bus clock, fixed system clock, external pin
- Clock prescaler taps for divide by 1, 2, 4, 8, 16, 32, 64, or 128
- 16-bit free-running or up/down (CPWM) count operation
- 16-bit modulus register to control counter range
- Timer system enable
- One interrupt per channel plus a terminal count interrupt for each TPM module (multiple TPMs device)
- Channel features:
  - — Each channel may be input capture, output compare, or buffered edge-aligned PWM
  - — Rising-edge, falling-edge, or any-edge input capture trigger
  - — Set, clear, or toggle output compare action
  - — Selectable polarity on PWM outputs

B.0.2 Block Diagram

Figure B-1 shows the structure of a TPM. Some MCUs include more than one TPM, with various numbers of channels.